

DSC-T77

SERVICE MANUAL

LEVEL 3

Ver. 1.0 2008.08

Revision History

Internal memory
ON BOARD



Photo: Black

*US Model
Canadian Model
AEP Model
UK Model
E Model
Australian Model
Hong Kong Model
Chinese Model
Korea Model
Argentine Model
Thai Model
Japanese Model
Tourist Model*

Link

• SERVICE NOTE

• PRINTED WIRING BOARDS

• REPAIR PARTS LIST

• SCHEMATIC DIAGRAMS

The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque \triangle sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

DIGITAL STILL CAMERA

SONY®

CAUTION

Danger of explosion if battery is incorrectly replaced.
Replace only with the same or equivalent type.

SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK \triangle OR DOTTED LINE WITH MARK \triangle ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

**ATTENTION AU COMPOSANT AYANT RAPPORT
À LA SÉCURITÉ!**

LES COMPOSANTS IDENTIFÉS PAR UNE MARQUE \triangle SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈSES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPLÉMENTS PUBLIÉS PAR SONY.

SAFETY CHECK-OUT

After correcting the original service problem, perform the following safety checks before releasing the set to the customer.

1. Check the area of your repair for unsoldered or poorly-soldered connections. Check the entire board surface for solder splashes and bridges.
2. Check the interboard wiring to ensure that no wires are "pinched" or contact high-wattage resistors.
3. Look for unauthorized replacement parts, particularly transistors, that were installed during a previous repair. Point them out to the customer and recommend their replacement.
4. Look for parts which, through functioning, show obvious signs of deterioration. Point them out to the customer and recommend their replacement.
5. Check the B+ voltage to see it is at the values specified.
6. Flexible Circuit Board Repairing
 - Keep the temperature of the soldering iron around 270°C during repairing.
 - Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
 - Be careful not to apply force on the conductor when soldering or unsoldering.

Unleaded solder

Boards requiring use of unleaded solder are printed with the lead-free mark (LF) indicating the solder contains no lead.

(Caution: Some printed circuit boards may not come printed with the lead free mark due to their particular size.)

: LEAD FREE MARK

Unleaded solder has the following characteristics.

- Unleaded solder melts at a temperature about 40°C higher than ordinary solder.
Ordinary soldering irons can be used but the iron tip has to be applied to the solder joint for a slightly longer time.
Soldering irons using a temperature regulator should be set to about 350°C.
Caution: The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!
- Strong viscosity
Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Usable with ordinary solder
It is best to use only unleaded solder but unleaded solder may also be added to ordinary solder.

1-1. PRECAUTION ON REPLACING THE SY-207 BOARD

DESTINATION DATA

When you replace to the repairing board, the written destination data of repairing board also might be changed to original setting. Refer to Service Manual ADJ, and perform “DESTINATION DATA WRITE”.

USB SERIAL No.

The set is shipped with a unique ID (USB Serial No.) written in it.

This ID has not been written in a new board for service, and therefore it must be entered after the board replacement.

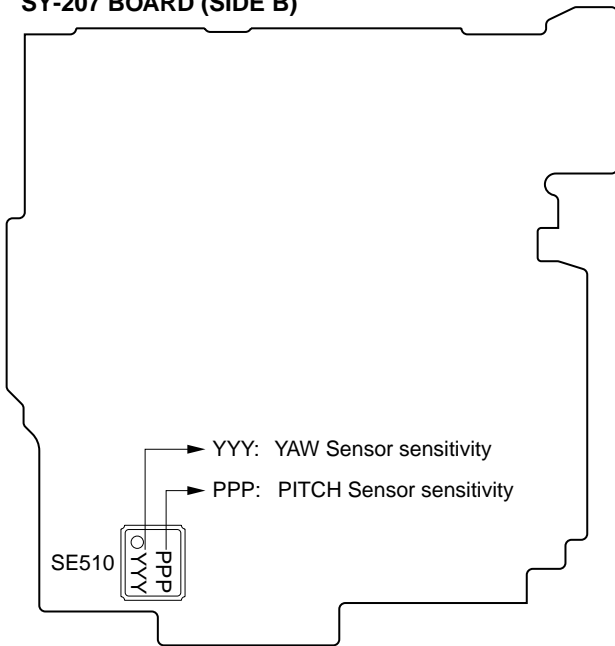
Refer to Service Manual ADJ, and perform “USB SERIAL No. INPUT”.

Angular Velocity Sensor

When you replace to the repairing board, write down the sensitivity displayed on the angular velocity sensor (SE510).

Refer to Service Manual ADJ, and perform “Angular velocity sensor sensitivity adj”.

SY-207 BOARD (SIDE B)



Note: The sensor sensitivity of SE510 of SY-207 board is written only repair parts.

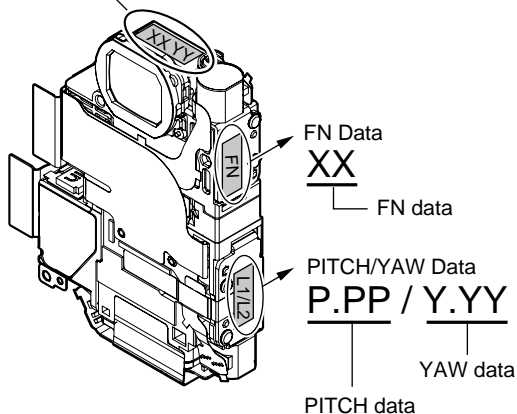
1-2. PRECAUTION ON REPLACING THE LENS

When replacing the lens, write down the PITCH/YAW data, FN data and wide limit data given on the data sheet of the replacement lens for service.

Refer to Service Manual ADJ, and perform “Wide Limit adj” and “Angular velocity sensor sensitivity adj”.

Wide Limit Data (2-byte data)

XXYY



Note: The PITCH/YAW data, FN data and wide limit data of lens are written only repair parts.

1-3. METHOD FOR COPYING OR ERASING THE DATA IN INTERNAL MEMORY

The data can be copied/erased by the operations on the HOME screen. (When erasing the data, execute formatting the internal memory.)

Note 1: When replacing the SY-207 board, erase the data in internal memory of the board before replacement.

Note 2: When replacing the SY-207 board, execute formatting and initialize the internal memory after replacement.

Method for Copying the Data in Internal Memory

Copy

Copies all images in the internal memory to a "Memory Stick Duo".

- 1 Insert a "Memory Stick Duo" into the camera.
- 2 **HOME** → **▼** (Manage Memory) → [Memory Tool] → **OK** → [Copy] → **OK** → [OK]



Notes

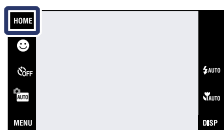
- Use a fully charged battery pack. If you attempt to copy image files using a battery pack with little remaining charge, the battery pack may run out, causing copying to fail or possibly corrupting the data.
- You cannot select images to copy.
- The original images in the internal memory are retained even after copying. To delete the contents of the internal memory, remove the "Memory Stick Duo" after copying, then format the internal memory ([Format] in [Memory Tool]).
- A new folder is created on the "Memory Stick Duo" and all the data will be copied to it. You cannot choose a specific folder and copy images to it.

Method for Formatting the Internal Memory

Format

Formats the "Memory Stick Duo" or the internal memory. A commercially available "Memory Stick Duo" is already formatted, and can be used immediately.

- 1 **HOME** → **▼** (Manage Memory) → [Memory Tool] → **OK** → [Format] → **OK** → [OK]



Notes

- Note that formatting permanently erases all data including even protected images.

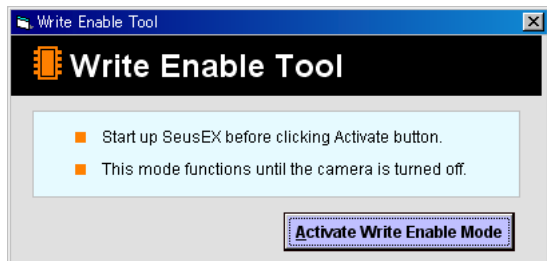
1-4. HOW TO WRITE DATA TO INTERNAL MEMORY

Usually, the camera has been set so as to disable the data writing from the PC to the internal memory of the camera.

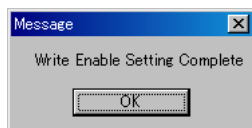
This setting must be changed temporarily when the data is to be written to the internal memory such as a case after the board replacement. To change the setting, use the write enable tool "WriteEnableTool.exe".

Data writing method

- 1) Connect the PC to the camera (USB mode: Mass Storage), and switch the driver to the "Sony Seus USB Driver".
- 2) Start the Write Enable Tool and the SeusEX.
- 3) Click the **Activate Write Enable Mode** button of the Write Enable Tool.



- 4) Upon completion of the setting change, the following message will be displayed.



- 5) Return the driver to the original one, and connect the PC to the camera (USB mode: Mass Storage).
- 6) Write the data read out into the PC to the internal memory of the camera.
- 7) Disconnect the PC from the camera, and turn off the camera.

Note: By turning off the camera, the write enable setting is reset.

1-6. PROCESS AFTER FIXING FLASH ERROR

When “FLASH error” (Self-diagnosis Code E : 91 : 01) occurs, to prevent any abnormal situation caused by high voltage, setting of the flash is changed automatically to disabling charge and flash setting.

After fixing, this setting needs to be deactivated. Flash error code can be initialized by the operations on the HOME screen.

Method for Initializing the Flash Error Code

Initialize

Initializes the setting to the default setting.

Even if you execute this function, the images are retained.

1 **HOME** →  (Settings) → [Main Settings] →
OK → [Initialize] → **OK** → [OK]



Notes

- Be sure not to turn off the camera while initializing.

1-1. SY-207基板交換時の注意

仕向けデータ

補修用基板と交換する時、補修用基板に書かれている仕向けデータは元の設定と違う場合があります。
ADJ編を参照して、「DESTINATION DATA WRITE」を行ってください。

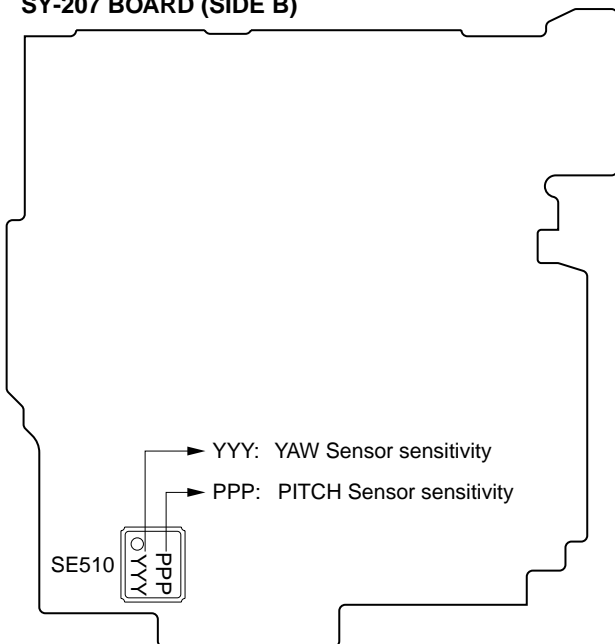
USBシリアルNo.

セットは、1台毎に異なる固有のID (USB Serial No.) を書き込んだ後、出荷されています。
新品の補修用基板には、このIDが書き込まれていないので、基板交換後にIDを入力する必要があります。
ADJ編を参照して、「USB SERIAL No. INPUT」を行ってください。

角速度センサ

補修用基板と交換する時、角速度センサ (SE510) の感度表示を書き留めてください。
ADJ編を参照して、「角速度センサ感度調整」を行ってください。

SY-207 BOARD (SIDE B)



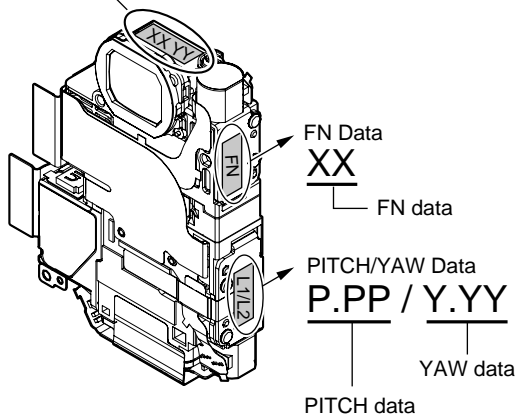
Note : SY-207基板のSE510感度表示は補修用基板にしか記載されておりません。

1-2. レンズ交換時の注意

レンズ交換時、補修用レンズ添付データシート掲載のPITCH/YAWデータ、FNデータおよびW端調整データを書き留めてください。
ADJ編を参照して、「W端調整」、「角速度センサ感度調整」を行ってください。

Wide Limit Data (2-byte data)

XXYY



Note : PITCH/YAWデータ、FNデータおよびW端調整データは、補修用部品にのみ記載されています。

1-3. 内蔵メモリーのデータコピーおよび消去方法

内蔵メモリーのデータコピーまたは消去はホーム画面の操作から実行可能です。（消去する場合は内蔵メモリーの初期化を行います。）

Note1：SY-207基板交換の際は、基板交換前に内蔵メモリーのデータを消去して下さい。

Note2：SY-207基板交換の際は、基板交換後に内蔵メモリーのフォーマットおよび初期化を実行して下さい。

内蔵メモリーのコピー方法

コピー

内蔵メモリーに記録した画像を、“メモリースティック デュオ”に一括コピーします。

- 1 “メモリースティック デュオ”を本機に入れる
- 2 HOME → (メモリー管理) → [メモリーツール] → OK → [コピー] → OK → [実行]



ご注意

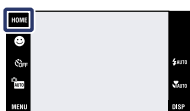
- 十分に充電したバッテリーをご使用ください。残量の少ないバッテリーを使用して画像ファイルのコピーすると、バッテリー切れのためデータを転送できなかったり、データを破損するおそれがあります。
- 画像ごとのコピーはできません。
- データをコピーしても、内蔵メモリー内のデータは削除されません。内蔵メモリーの内容を消去するには、コピー後に“メモリースティック デュオ”を本体から取りはずし、[メモリーツール]の[フォーマット]を行ってください。
- データをコピーすると“メモリースティック デュオ”内に新しいフォルダが作成されます。コピー先のフォルダを指定することはできません。

内蔵メモリーのフォーマット方法

フォーマット

“メモリースティック デュオ”または内蔵メモリーをフォーマット（初期化）します。市販の“メモリースティック デュオ”はフォーマット済みのため、フォーマットの必要はありません。

- 1 HOME → (メモリー管理) → [メモリーツール] → OK → [フォーマット] → OK → [実行]



ご注意

- フォーマットすると、プロテクトしてある画像も含めて、すべてのデータが消去され、元に戻せません。

1-4. 内蔵メモリーへデータを書き戻す方法

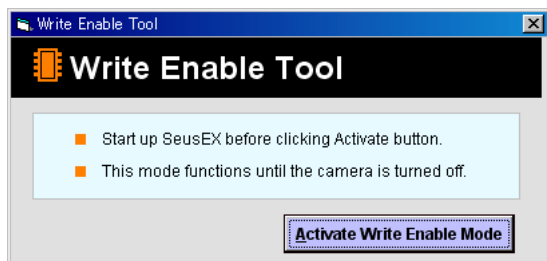
通常は、PCからカメラの内蔵メモリーへデータを書き込むことはできない設定になっています。

基板交換後などに、内蔵メモリーへデータを書き戻す場合には、この設定を一時的に変更する必要があります。

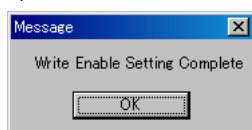
設定の変更には、書き込み許可ツール（WriteEnableTool.exe）を使用します。

書き戻し方法

- 1) カメラとPCをマストレージ接続し、ドライバを“Sony Seus USB Driver”に切り替える。
- 2) 書き込み許可ツールとSeusEXを起動する。
- 3) 書き込み許可ツールの[Activate Write Enable Mode]ボタンをクリックする。



- 4) 設定の変更が終了すると、次のメッセージが表示されます。



- 5) ドライバを元に戻して、カメラとPCをマストレージ接続する。
- 6) PCに読み出しておいたデータをカメラの内蔵メモリーに書き込む。
- 7) カメラとPCの接続を解除し、カメラの電源をOFFにする。

注意：カメラの電源をOFFにすることにより、書き込み許可の設定が解除されます。

1-6. フラッシュエラー発生時の対処法

本機はフラッシュエラー（自己診断コードE：91：01）が発生した場合、高電圧による異常を防止するために自動的にフラッシュ充電および発光禁止の設定になります。

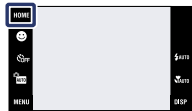
フラッシュエラー発生後はエラーの解除を行う必要があります。エラーの解除はホーム画面から初期化操作を実行することにより行います。

フラッシュエラーの解除方法

設定リセット

お買い上げ時の設定に戻します。
[設定リセット]を実行しても、画像は削除されません。

1 HOME → (設定) → [本体設定] → OK
→ [設定リセット] → OK → [実行]



ご注意

- ・ 設定リセット中は電源が切れないようにご注意ください。

4-2. SCHEMATIC DIAGRAMS

Link

<ul style="list-style-type: none">• CD-743 FLEXIBLE BOARD (CCD IMAGER)	<ul style="list-style-type: none">• SY-207 BOARD(5/9) (CPU (SIGNAL PROCESS 3))
<ul style="list-style-type: none">• SY-207 BOARD(1/9) (DC/DC CONVERTER)	<ul style="list-style-type: none">• SY-207 BOARD(6/9) (CCD SIGNAL PROCESS)
<ul style="list-style-type: none">• SY-207 BOARD(2/9) (BATTERY DETECTOR/CLOCK GENERATOR)	<ul style="list-style-type: none">• SY-207 BOARD(7/9) (OIS DRIVE)
<ul style="list-style-type: none">• SY-207 BOARD(3/9) (CPU (SIGNAL PROCESS 1))	<ul style="list-style-type: none">• SY-207 BOARD(8/9) (AUDIO/VIDEO AMP)
<ul style="list-style-type: none">• SY-207 BOARD(4/9) (CPU (SIGNAL PROCESS 2))	<ul style="list-style-type: none">• SY-207 BOARD(9/9) (CONNECTOR)

- COMMON NOTE FOR SCHEMATIC DIAGRAMS

(JAPANESE)

回路図共通ノート

(他に必要なノートは各ブロックに記載してあります)

【回路図ノート】

- ・ケミコン、タンタルを除くコンデンサで、耐圧50V以下のものはその耐圧を省略。単位はすべて μF (pはpF)。
- ・チップ抵抗で指示のないものは、1/10W以下。
k = 1000 , M = 1000k
- ・チップ部品交換時の注意
取り外した部品は再使用せず、未使用の部品をご使用ください。

タンタルコンデンサのマイナス側は熱に弱いので注意してください。








- ・チップ部品には下記のように表示したものがあります。

例	C 541	L 452
	22U	10UH
	TA A	2520

種類 ケースサイズ 外形寸法 (mm)

- ・抵抗、コンデンサ、ICなど定数にXXがあるものは、使用していない事を示しています。このため、使用していない回路が記載されている事があります。
- ・印のある部品は、機種などにより異なりますので機能別マウント一覧表を参照してください。
- ・可変抵抗と半固定抵抗で、B特性の表示を省略。
- ・信号名表記について、下記のような場合があります。

XEDIT EDIT PB/XREC PB/REC

- ・は不燃性抵抗。
- ・はヒューズ抵抗。
- ・はパネル表示名称。
- ・はB+ライン。
- ・はB-ライン。
- ・はBライン (+, -) の入出力方向を示す。
- ・は調整名称。

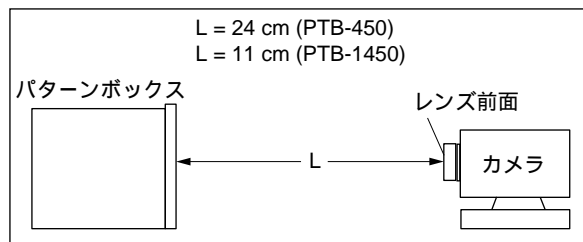
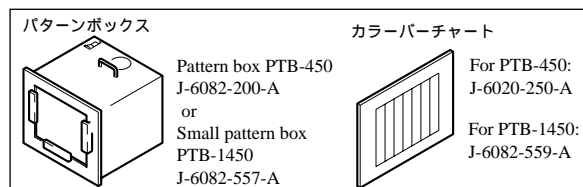
【電圧・波形測定条件ノート】

- ・電圧値及び信号波形はパターンボックスのカラーバーチャートを被写体としたときの測定点对アース間の参考値。
(デジタルマルチメータ; 入力インピーダンス DC10M Ω 使用)
- ・使用テストの入力インピーダンスにより電圧値が多少異なります。

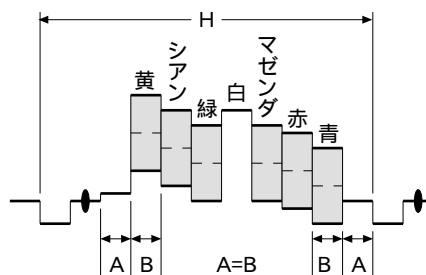
イメージ交換時の注意

- ・イメージを交換した場合は、カメラ部の全調整を行ってください。
 - ・イメージは構造上、静電気により破壊される恐れがあるため、MOS ICと同様に注意して取り扱ってください。
- また、受光部にはゴミの付着、および強い光がはいることのないように注意してください。

1. 接続図

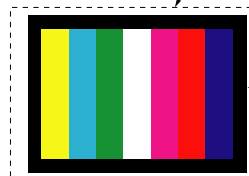


2. 図a及び図bの波形が得られるように画枠調整して下さい。



図a (映像入出力端子出力波形)

電子ビーム走査線

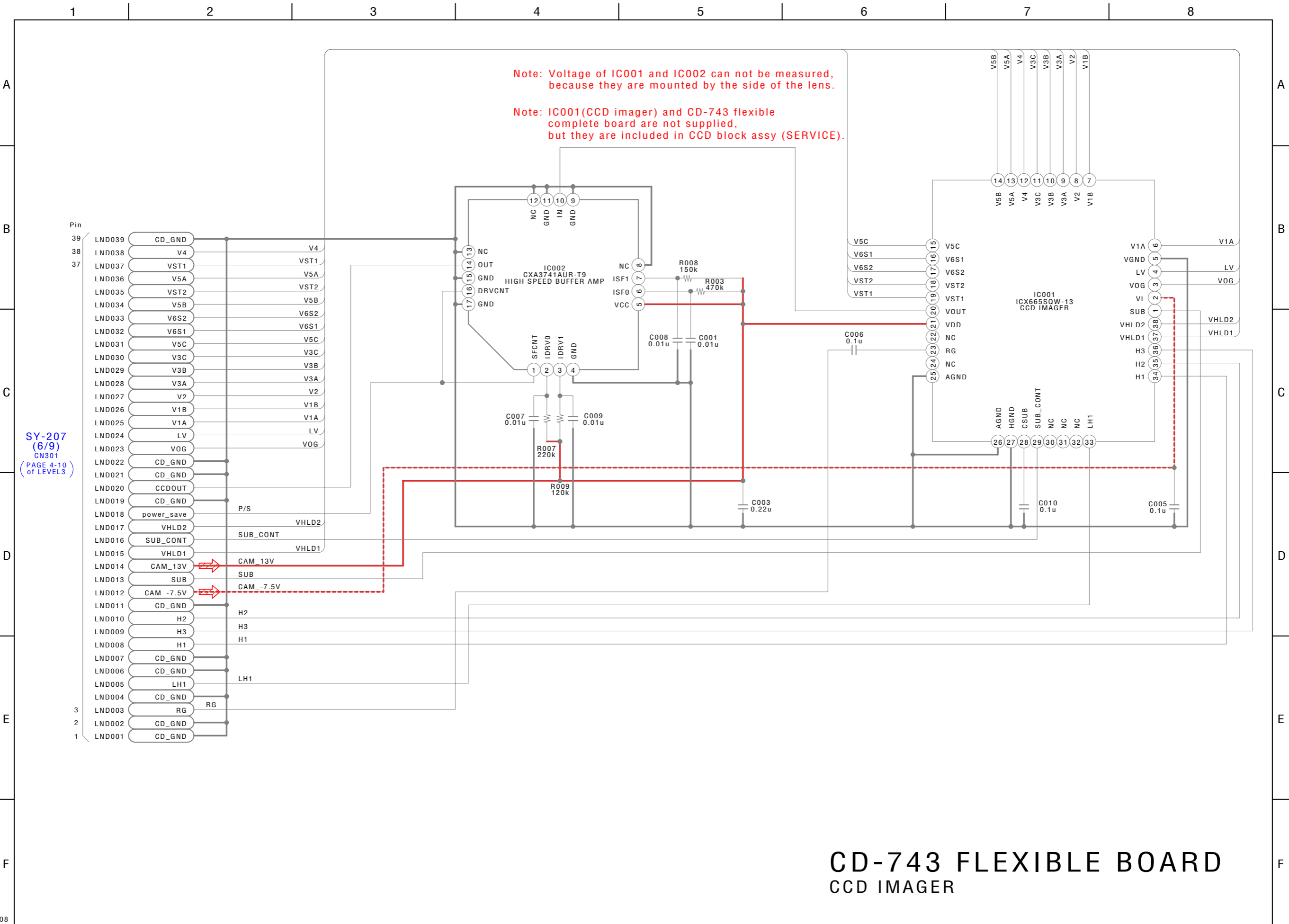


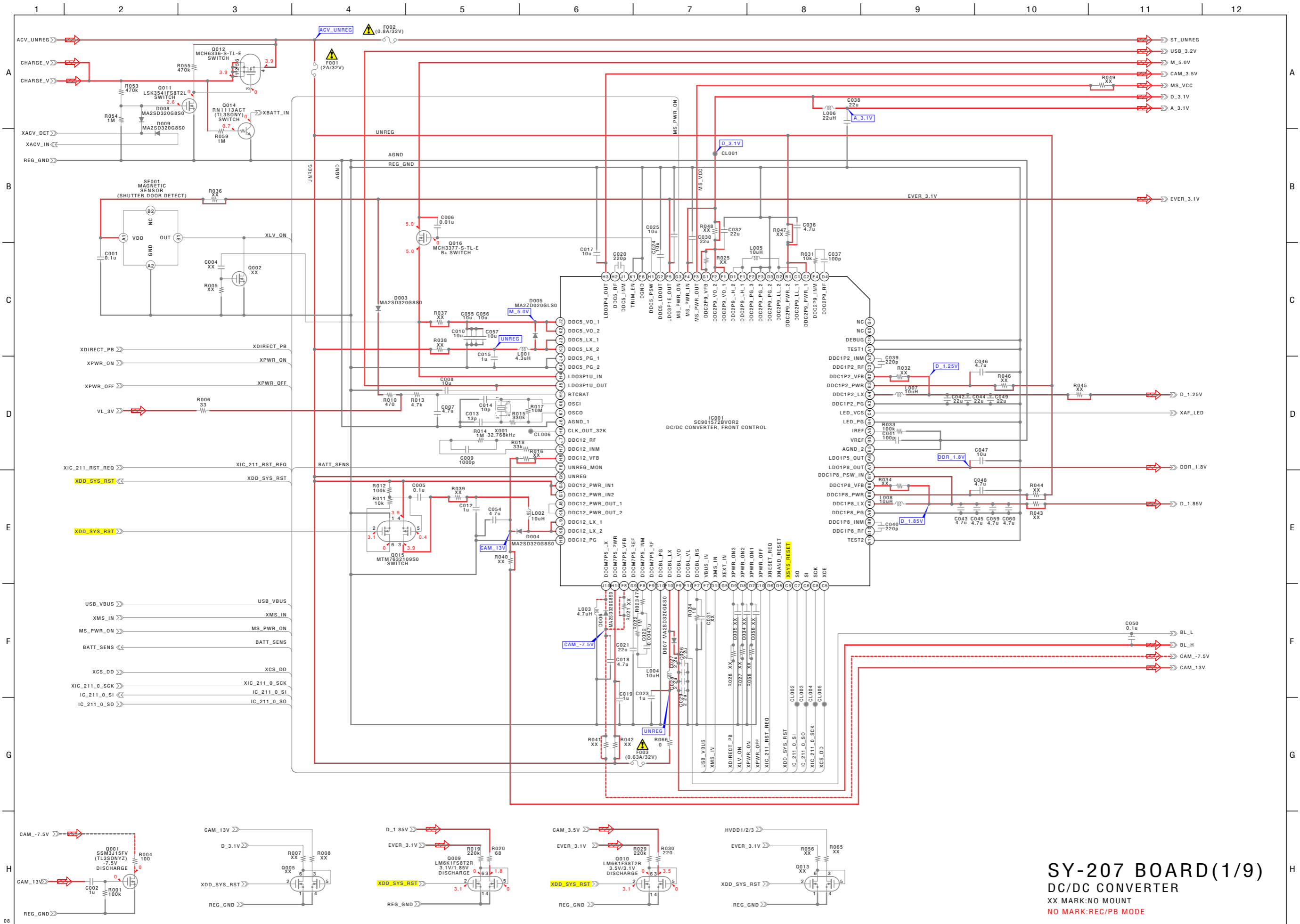
図b (テレビモニタの映像)

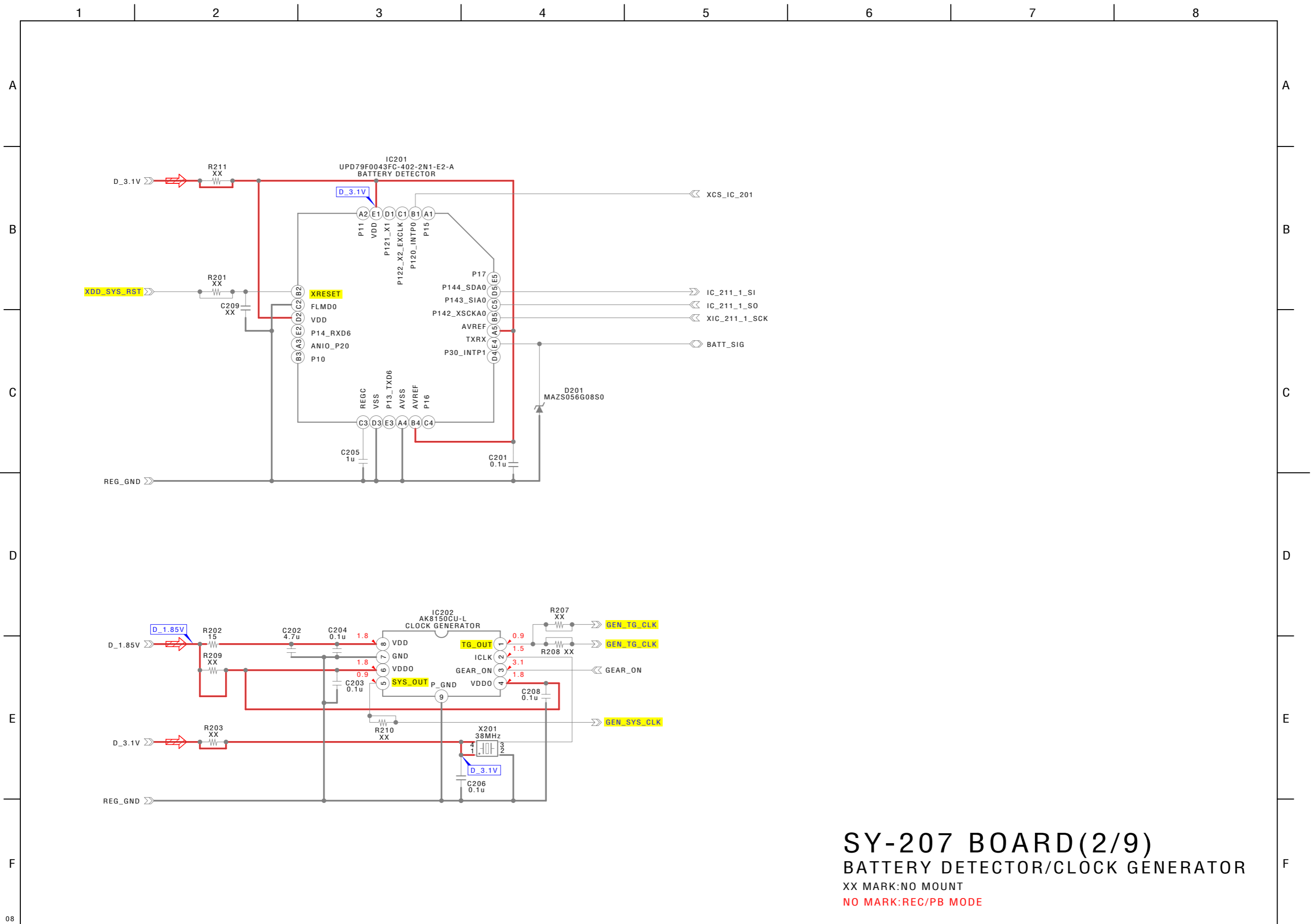
△印の部品、または△印付きの点線で囲まれた部品は、安全性を維持するために重要な部品です。従って交換時は、必ず指定の部品を使用して下さい。

お願い

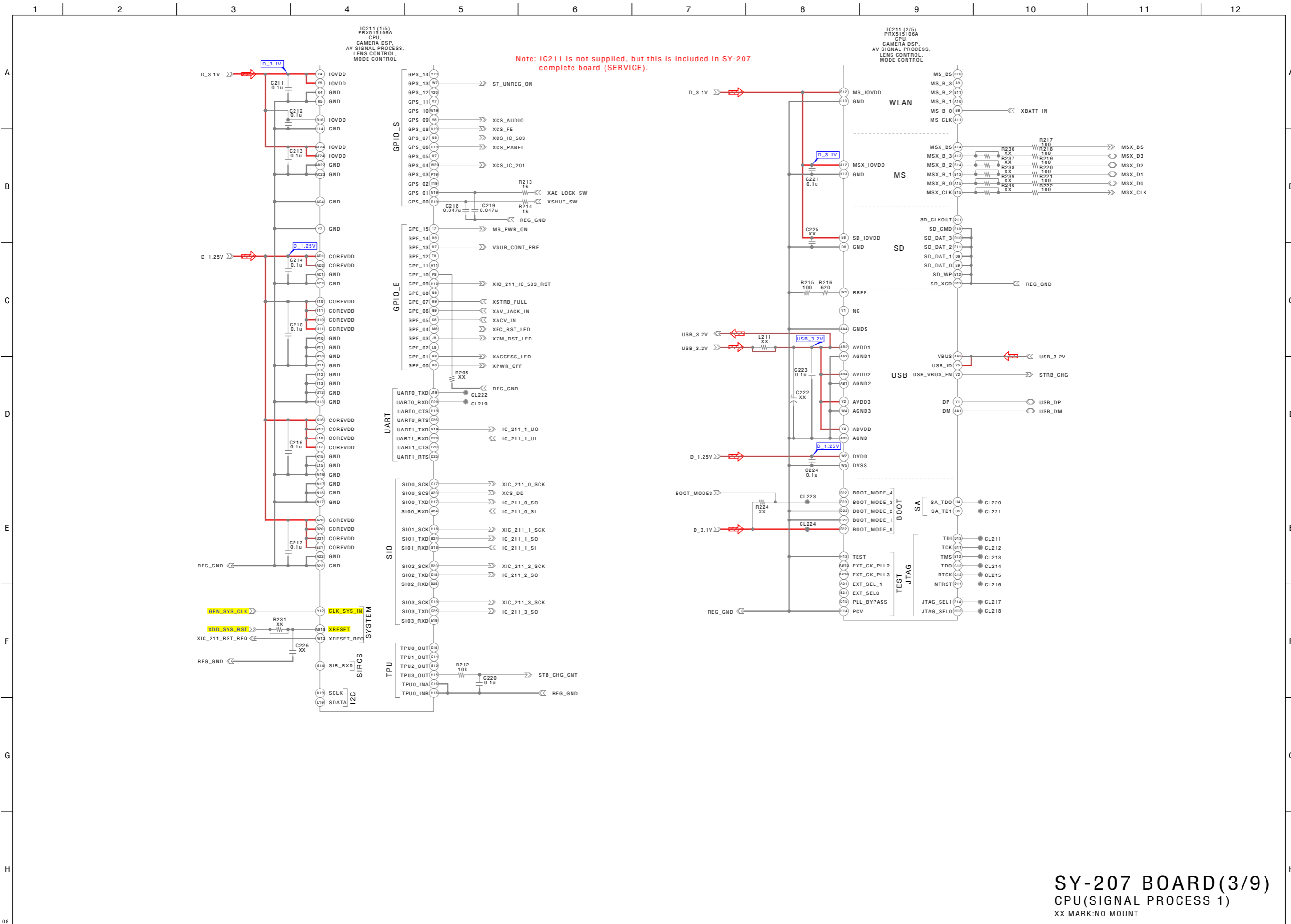
図面番号で部品を指定するときは基板名又はブロックを併せて指定して下さい。



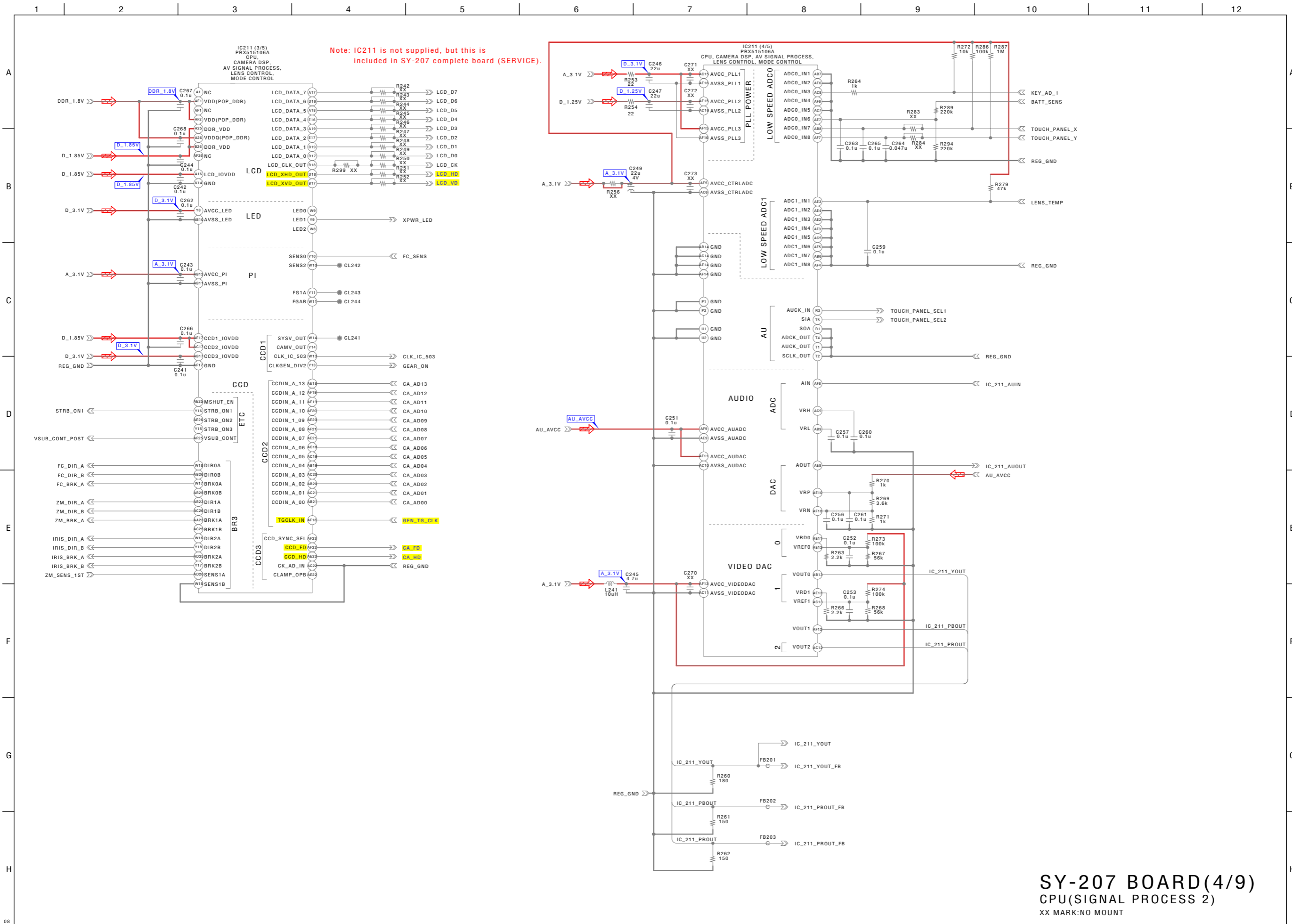




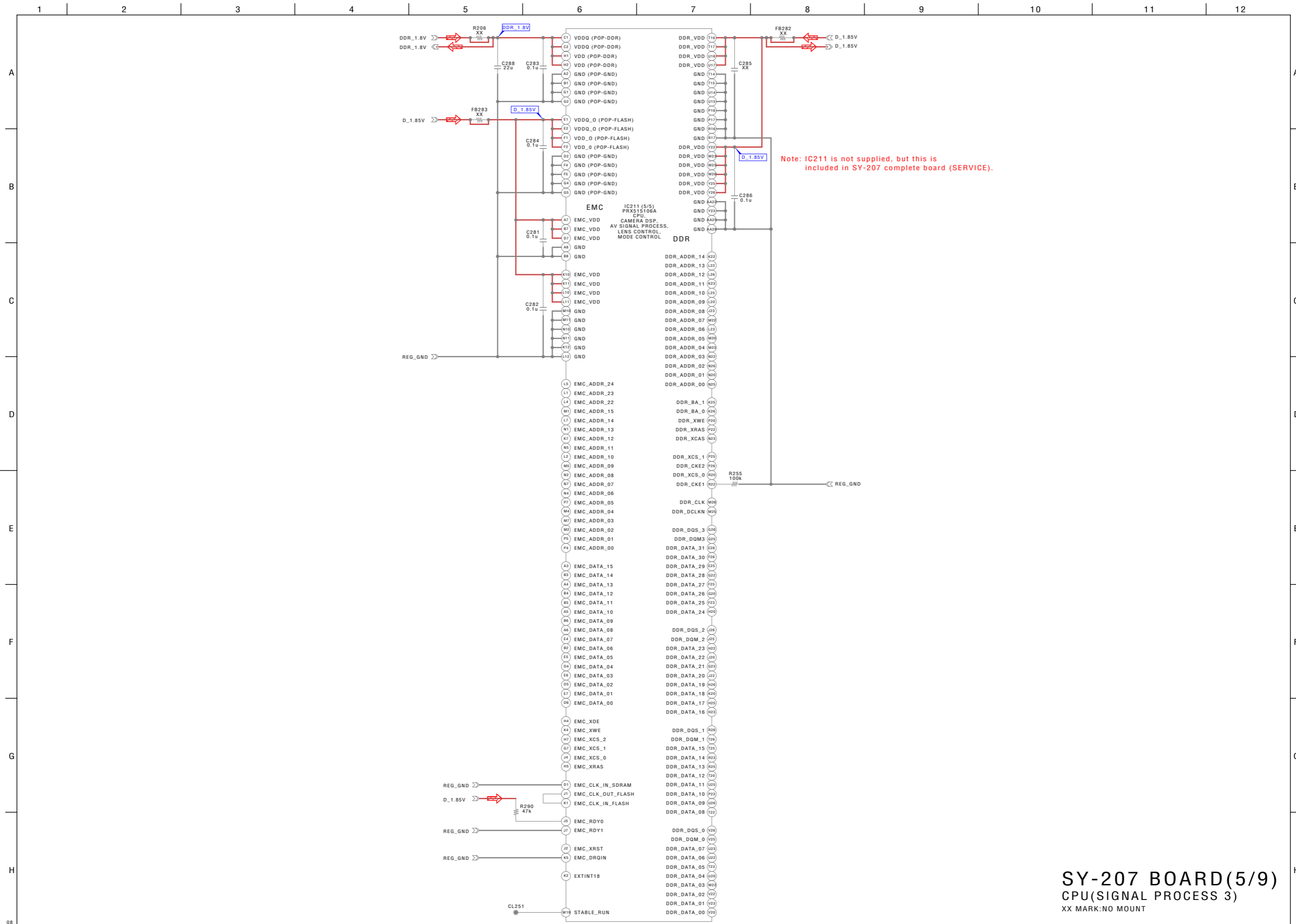
SY-207 BOARD(2/9)
BATTERY DETECTOR/CLOCK GENERATOR
 XX MARK:NO MOUNT
 NO MARK:REC/PB MODE



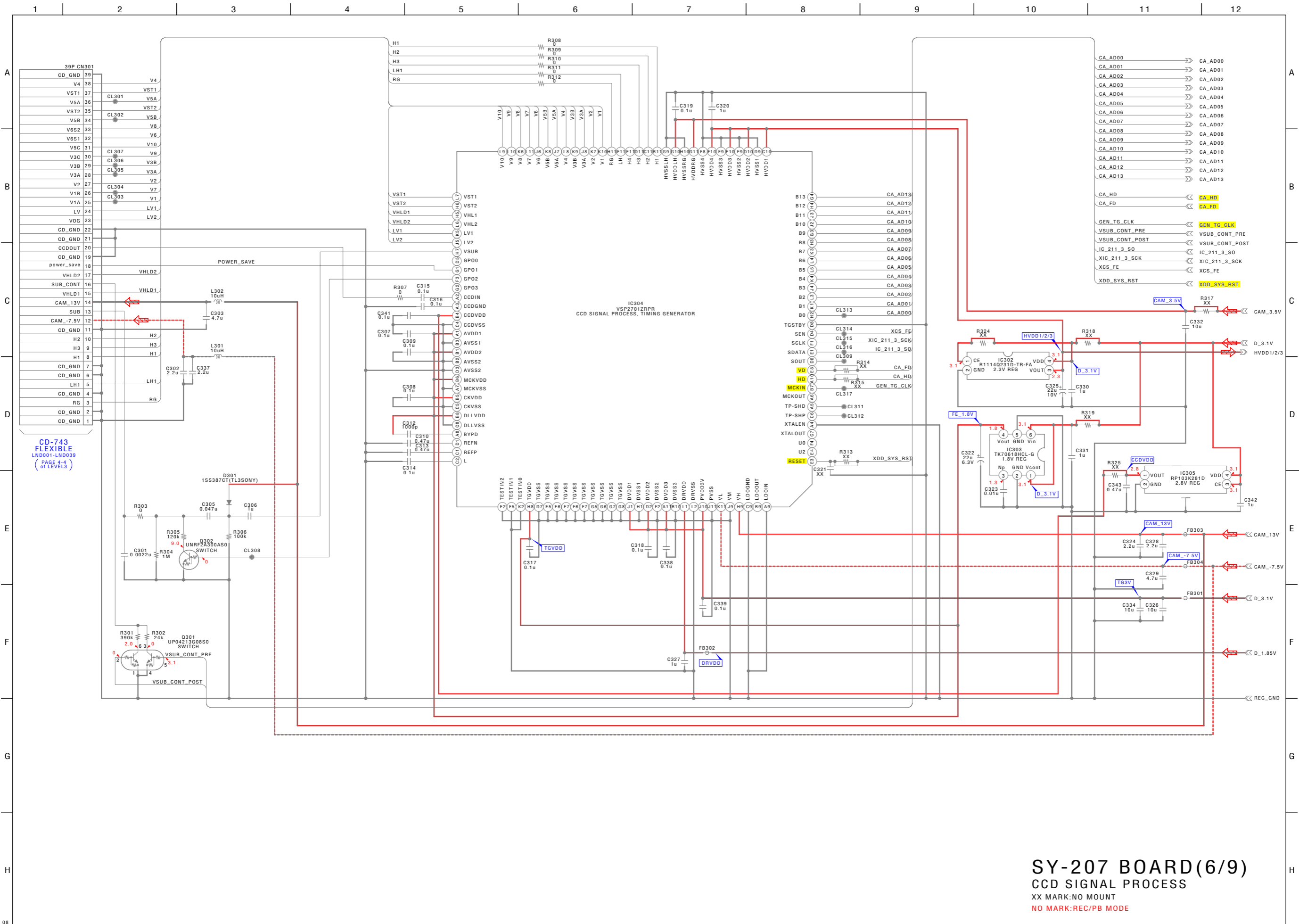
SY-207 BOARD(3/9)
 CPU(SIGNAL PROCESS 1)
 XX MARK:NO MOUNT

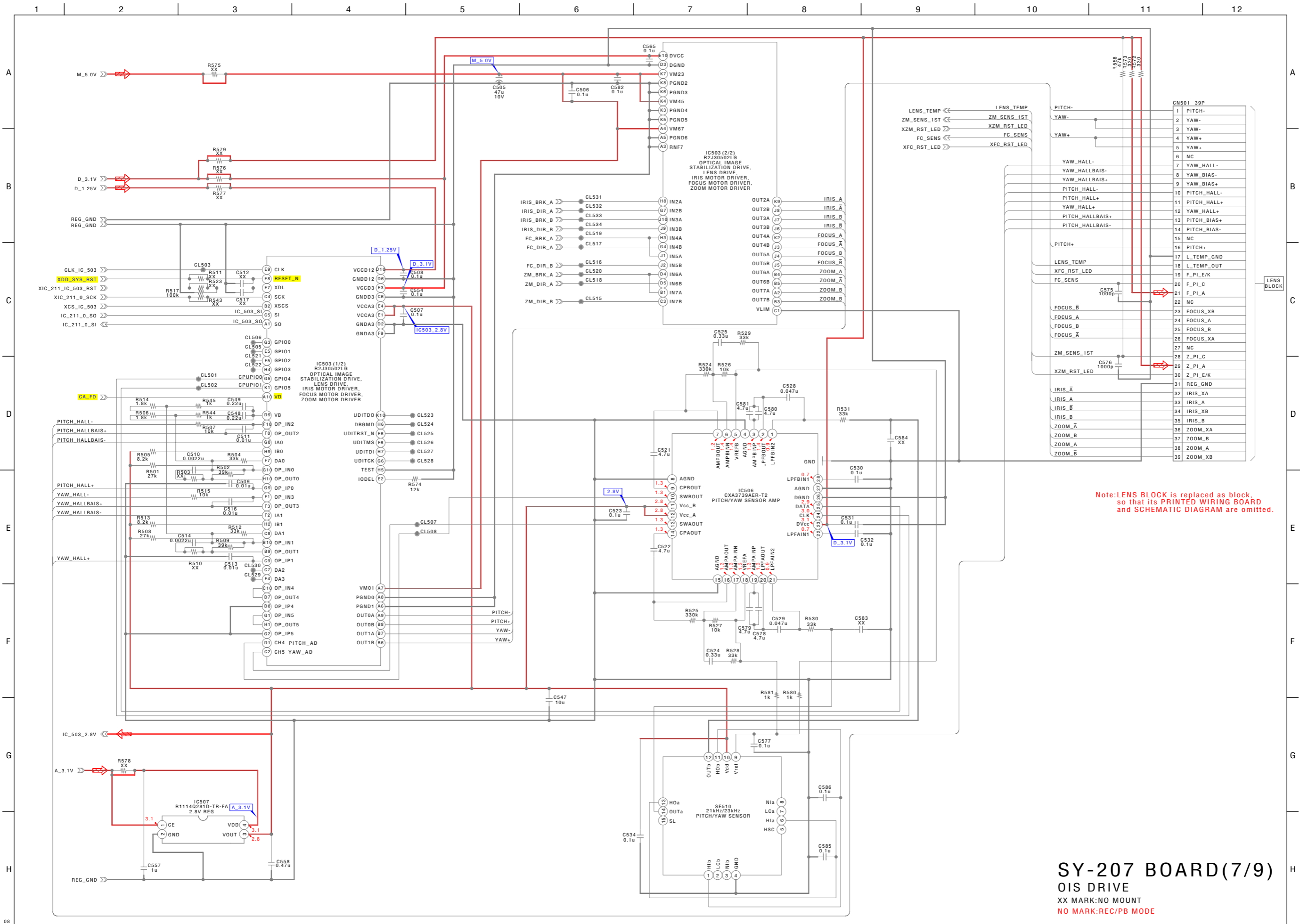


SY-207 BOARD(4/9)
CPU(SIGNAL PROCESS 2)
XX MARK:NO MOUNT



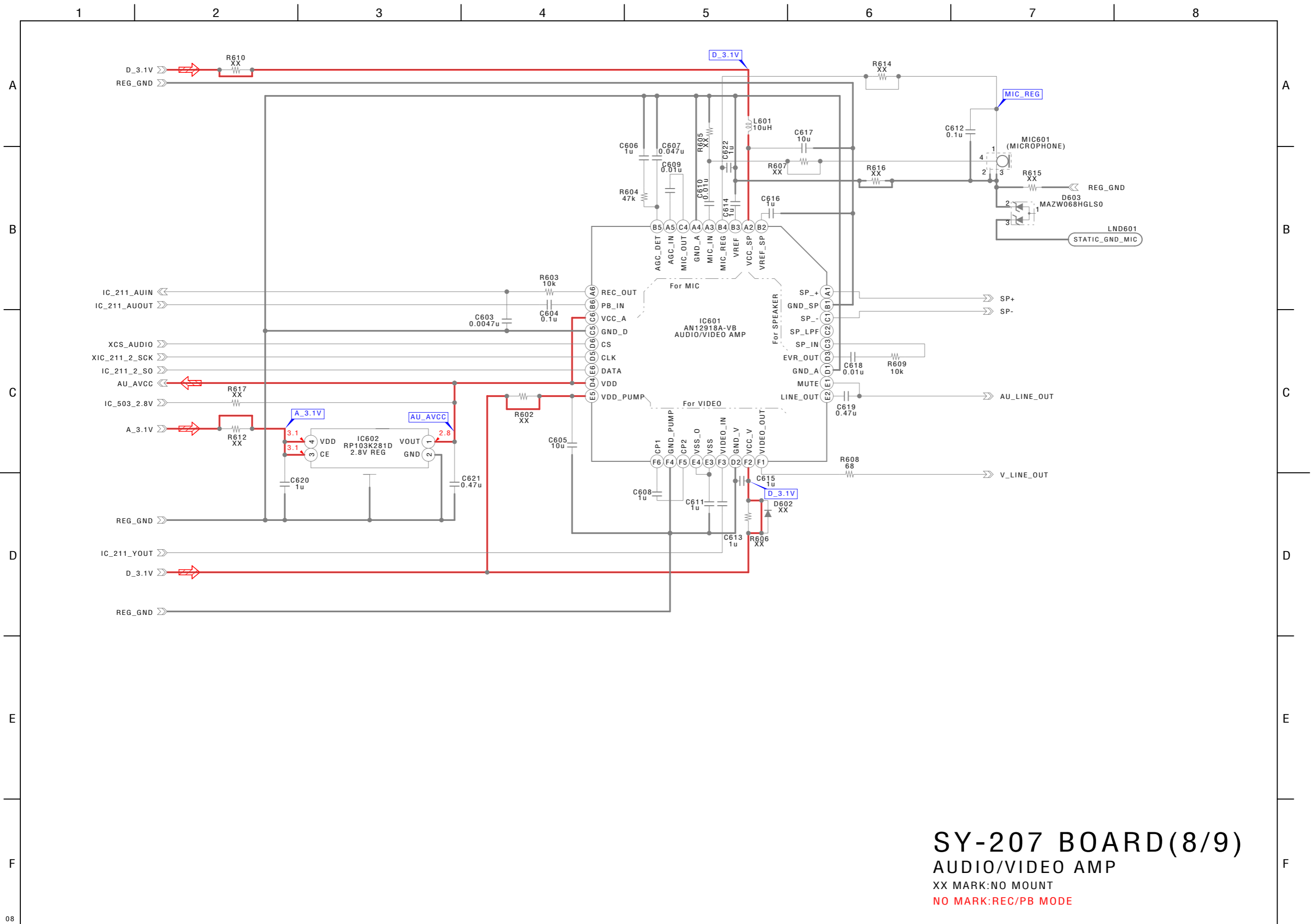
SY-207 BOARD(5/9)
 CPU(SIGNAL PROCESS 3)
 XX MARK:NO MOUNT



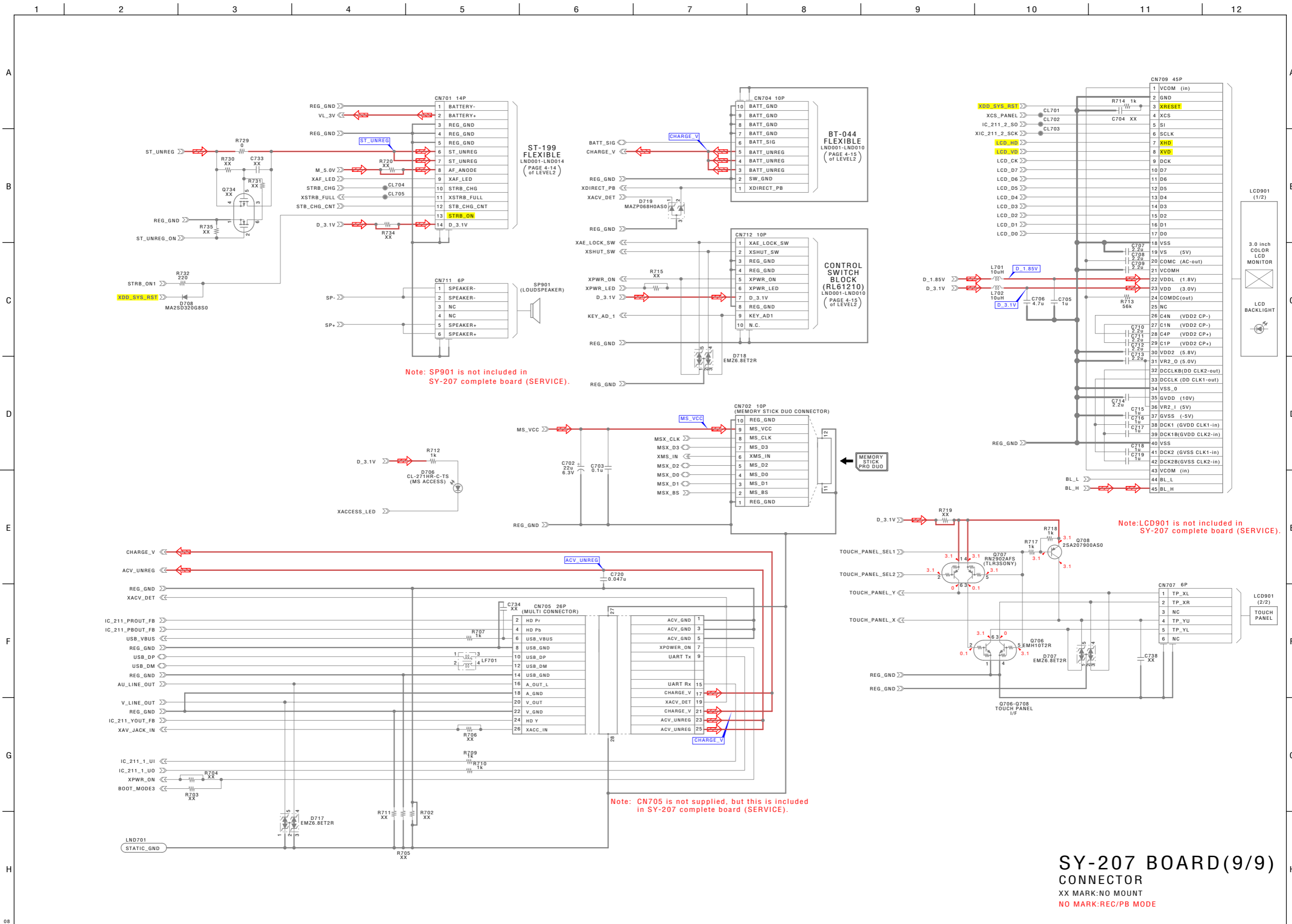


Note: LENS BLOCK is replaced as block, so that its PRINTED WIRING BOARD and SCHEMATIC DIAGRAM are omitted.

SY-207 BOARD (7/9)
OIS DRIVE
 XX MARK: NO MOUNT
 NO MARK: REC/PB MODE



SY-207 BOARD(8/9)
AUDIO/VIDEO AMP
 XX MARK:NO MOUNT
 NO MARK:REC/PB MODE



SY-207 BOARD(9/9)
CONNECTOR
 XX MARK:NO MOUNT
 NO MARK:REC/PB MODE

4-3. PRINTED WIRING BOARDS

Link

• [CD-743 FLEXIBLE BOARD](#)

• [SY-207 BOARD \(SIDE B\)](#)

• [SY-207 BOARD \(SIDE A\)](#)







• [COMMON NOTE FOR PRINTED WIRING BOARDS](#)

4-3. PRINTED WIRING BOARDS

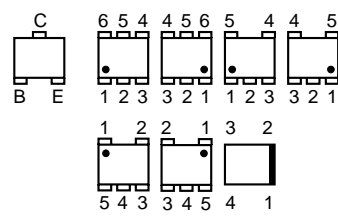
4-3. PRINTED WIRING BOARDS

(ENGLISH)

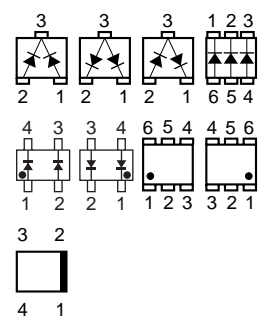
THIS NOTE IS COMMON FOR PRINTED WIRING BOARDS

-  : Uses unleaded solder.
-  : Circuit board
-  : Flexible board
-  : Pattern from the side which enables seeing.
-  : pattern of the rear side
(The other layers' patterns are not indicated)
- Through hole is omitted.
- Circled numbers refer to waveforms.
- There are a few cases that the part printed on diagram isn't mounted in this model.
-  : panel designation

- Chip parts.









Diode



(JAPANESE)

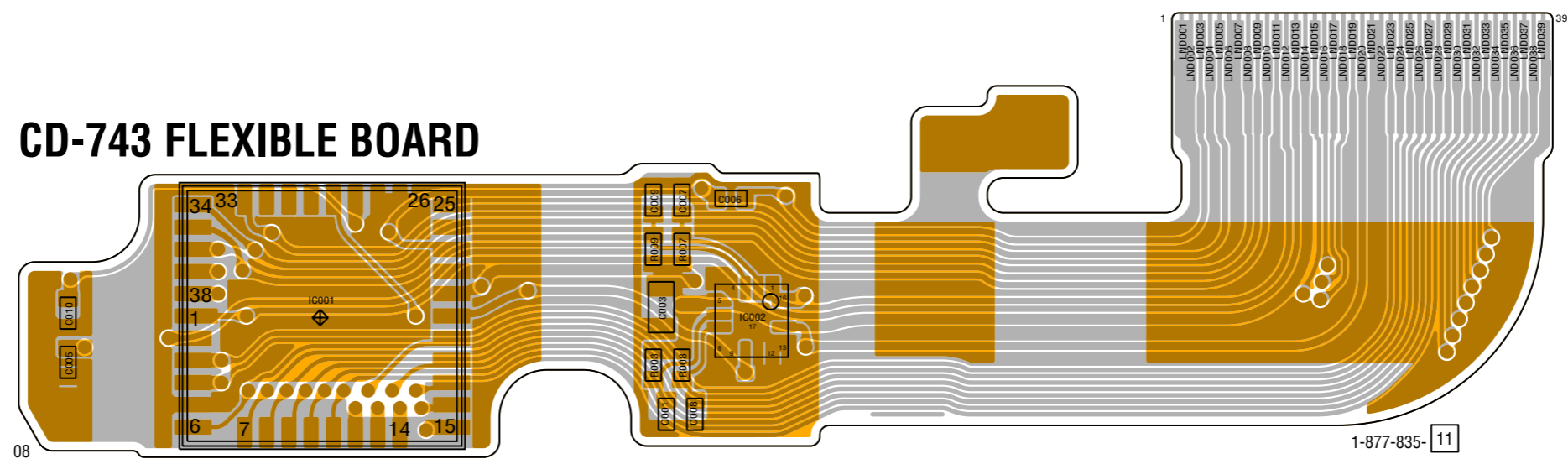
プリント図共通ノート

【プリント図ノート】

-  : 無鉛半田を使用しています。
-  : 基板
-  : フレキシブル配線板
-  : 見ている面側のパターン。
-  : 裏側のパターン
(他のパターンについては表示されていません)
- スルーホールは省略。
- プリント図には、本機で使用していない部品が記載されている場合があります。
-  はパネル表示名称。

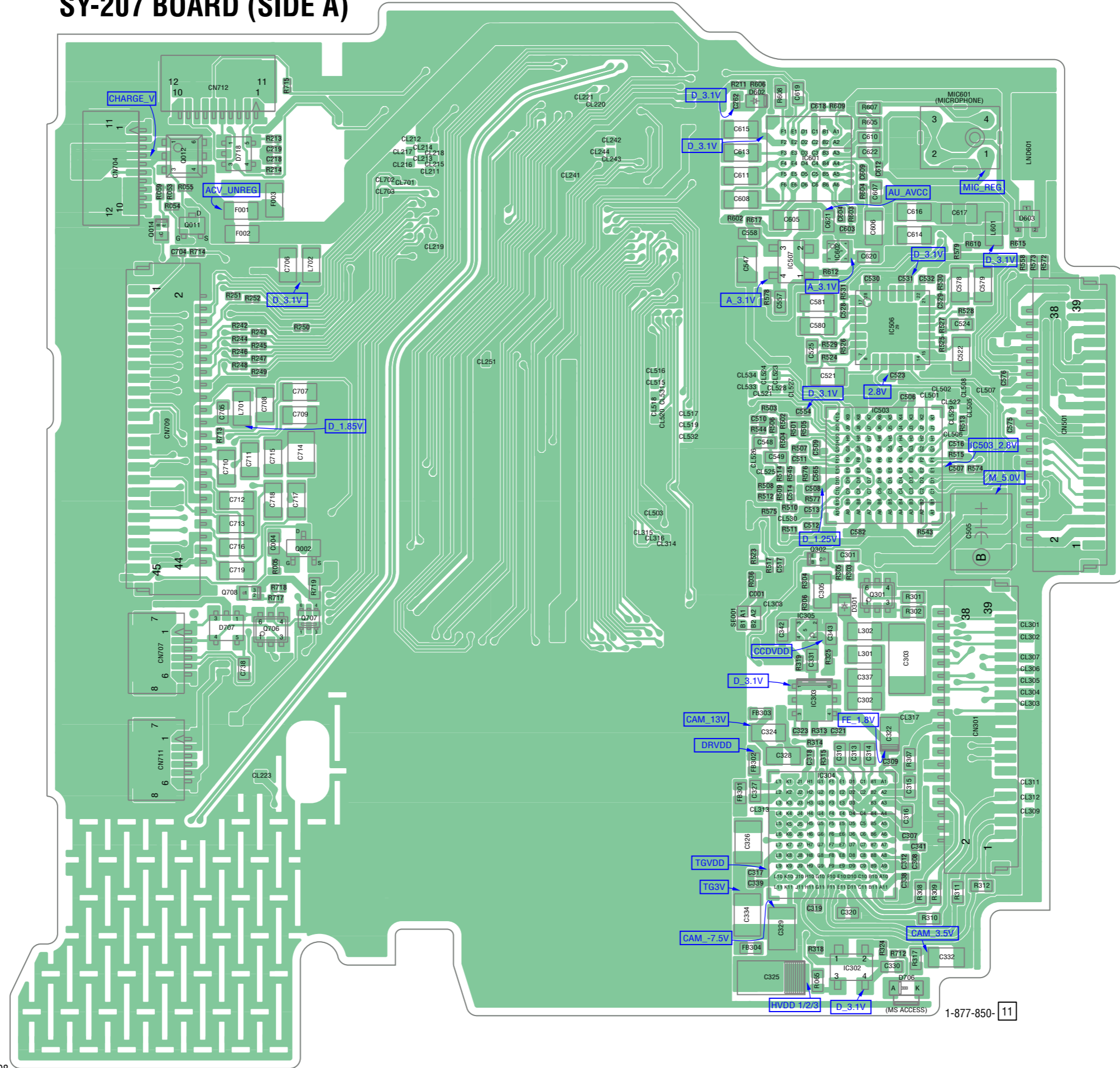
CD-743 (3 layers)

 : Uses unleaded solder.

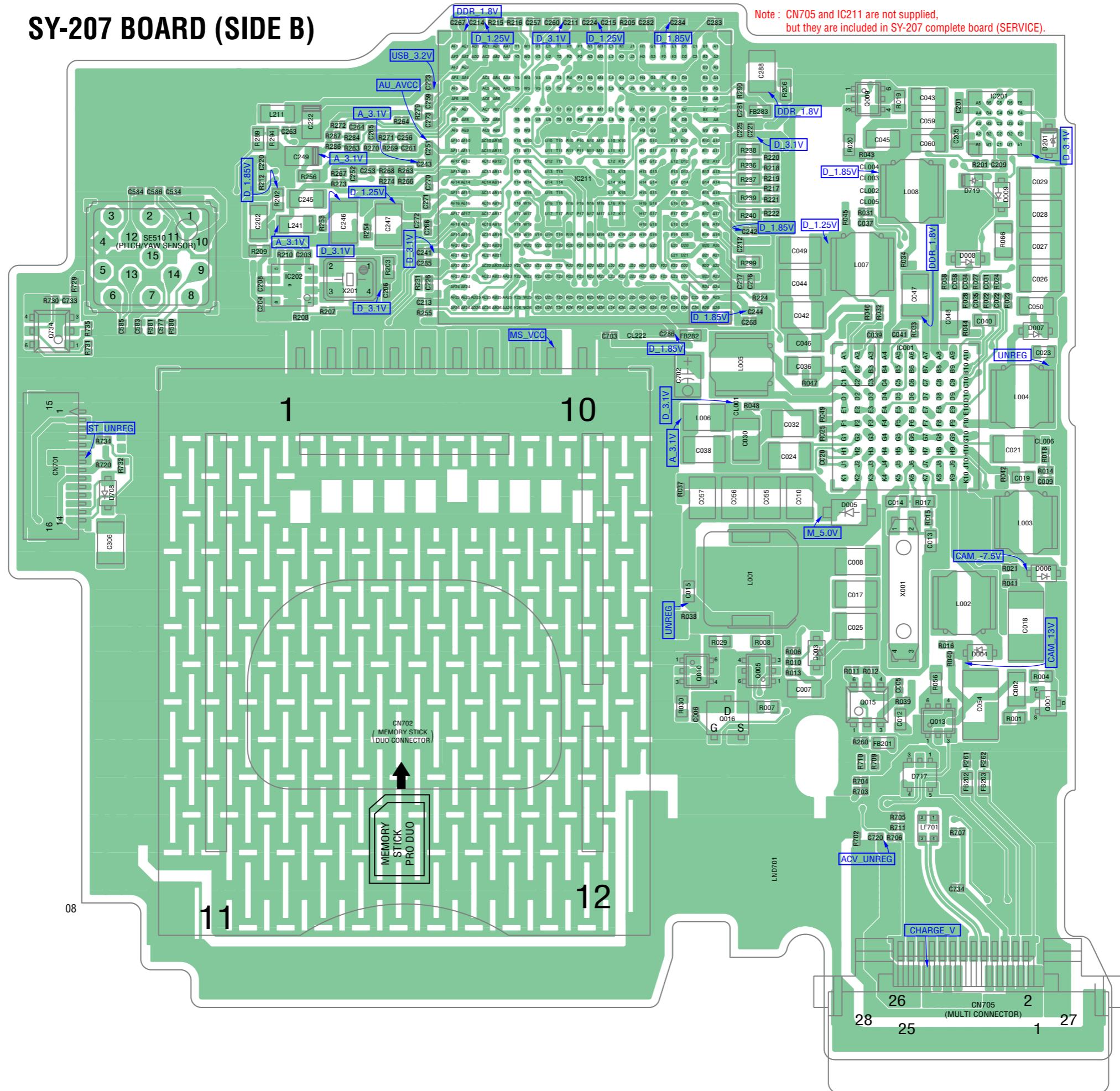


Note : IC001 (CCD imager) and CD-743 flexible complete board are not supplied, but they are included in CCD block assy (SERVICE).

SY-207 BOARD (SIDE A)



SY-207 BOARD (SIDE B)



Note : CN705 and IC211 are not supplied,
but they are included in SY-207 complete board (SERVICE).

5. REPAIR PARTS LIST

(ENGLISH)

NOTE:

- -XX, -X mean standardized parts, so they may have some differences from the original one.
- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.
- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- CAPACITORS:
uF: μ F
- COILS
uH: μ H
- RESISTORS
All resistors are in ohms.
METAL: metal-film resistor
METAL OXIDE: Metal Oxide-film resistor
F: nonflammable
- SEMICONDUCTORS
In each case, u: μ , for example:
uA...: μ A..., uPA..., μ PA...,
uPB..., μ PB..., μ PC..., μ PC...,
uPD..., μ PD...

(JAPANESE)

【使用上の注意】

- ここに記載されている部品は、補修用部品であるため、回路図及びセットに付いている部品と異なる場合があります。
- -XX, -Xは標準化部品のため、セットに付いている部品と異なる場合があります。
- *印の部品は常備在庫しておりません。
- コンデンサの単位でuFは μ Fを示します。
- 抵抗の単位は省略してあります。
金 被：金属被膜抵抗。
サンキン：酸化金属被膜抵抗。
- インダクタの単位でuHは μ Hを示します。
- 半導体の名称でuA..., uPA..., uPB..., uPC..., uPD...等はそれぞれA..., μ PA..., μ PB..., μ PC..., μ PD...を示します。

• Abbreviation

- AR : Argentine model
- AUS : Australian model
- BR : Brazilian model
- CH : Chinese model
- CND : Canadian model
- EE : East European model
- HK : Hong Kong model
- J : Japanese model
- JE : Tourist model
- KR : Korea model
- NE : North European model
- TH : Thai model
- TW : Taiwan model

When indicating parts by reference number, please include the board name.

The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque \triangle sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

• Color Indication of Appearance Parts

Example:

(SILVER) : Cabinet's Color

(Silver) : Parts Color

お願い

図面番号で部品を指定するときは基板名又はブロックを併せて指定してください。

\triangle 印の部品、または \triangle 印付の点線で囲まれた部品は、安全性を維持するために、重要な部品です。従って交換時は必ず指定の部品を使用してください。

5-2. ELECTRICAL PARTS LIST

Ref. No.	Part No.	Description
	A-1558-183-A	CCD BLCOK ASSY (SERVICE)
	(Not supplied)	CD-743 FLEXIBLE BOARD, COMPLETE

(IC001 (CCD imager) and CD-743 flexible complete board are not supplied, but they are included in CCD block assy (SERVICE).)

< CAPACITOR >

C001	1-100-567-81	CERAMIC CHIP	0.01uF	10%	25V
C003	1-127-715-11	CERAMIC CHIP	0.22uF	10%	16V
C005	1-125-777-11	CERAMIC CHIP	0.1uF	10%	10V
* C006	1-114-582-11	CERAMIC CHIP	0.1uF	10%	16V
C007	1-100-567-81	CERAMIC CHIP	0.01uF	10%	25V
C008	1-100-567-81	CERAMIC CHIP	0.01uF	10%	25V
C009	1-100-567-81	CERAMIC CHIP	0.01uF	10%	25V
* C010	1-114-582-11	CERAMIC CHIP	0.1uF	10%	16V

< IC >

IC001	(Not supplied)	ICX665SQW-13 (CCD IMAGER)
(IC001 is supplied including in CCD BLOCK ASSY (SERVICE).)		
* IC002	8-753-294-89	IC CXA3741AUR-T9

< RESISTOR >

R003	1-218-985-11	RES-CHIP	470K	5%	1/16W
R007	1-218-981-91	RES-CHIP	220K	5%	1/16W
R008	1-218-979-11	RES-CHIP	150K	5%	1/16W
R009	1-218-978-11	RES-CHIP	120K	5%	1/16W

ノート: イメージャの交換時は4-3ページの“イメージャ交換時の注意”を必ずお読みください。

Note: Be sure to read "Precautions for Replacement of Imager" on page 4-2 when changing the imager.

Ref. No.	Part No.	Description				
	A-1557-174-A	SY-207 BOARD, COMPLETE (SERVICE)				

(CN705 and IC211 are not supplied, but they are included in SY-207 complete board (SERVICE).)						
< CAPACITOR >						
* C001	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C002	1-112-298-91	CERAMIC CHIP	1uF	10%	16V	
* C005	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C006	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V	
* C007	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C008	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C009	1-128-627-11	CERAMIC CHIP	1000PF	10%	16V	
C010	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C012	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V	
* C013	1-128-965-11	CERAMIC CHIP	13PF	5%	50V	
C014	1-164-850-11	CERAMIC CHIP	10PF	0.5%	50V	
C015	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V	
C017	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
* C018	1-114-796-91	CERAMIC CHIP	4.7uF	10%	16V	
C019	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V	
C020	1-128-623-11	CERAMIC CHIP	220PF	10%	16V	
C021	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C022	1-128-630-11	CERAMIC CHIP	0.0047uF	10%	6.3V	
C023	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V	
C024	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C025	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C026	1-114-098-91	CERAMIC CHIP	2.2uF	20%	25V	
C027	1-114-098-91	CERAMIC CHIP	2.2uF	20%	25V	
C028	1-114-098-91	CERAMIC CHIP	2.2uF	20%	25V	
C029	1-114-098-91	CERAMIC CHIP	2.2uF	20%	25V	
C030	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C032	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
* C036	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C037	1-128-622-91	CERAMIC CHIP	100PF	10%	16V	
C038	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C039	1-128-623-11	CERAMIC CHIP	220PF	10%	16V	
C040	1-164-933-11	CERAMIC CHIP	220PF	10%	50V	
C041	1-128-622-91	CERAMIC CHIP	100PF	10%	16V	
C042	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
* C043	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C044	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
* C045	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
* C046	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C047	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
* C048	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C049	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C050	1-100-566-91	CERAMIC CHIP	0.1uF	10%	25V	
* C054	1-114-796-91	CERAMIC CHIP	4.7uF	10%	16V	
C055	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C056	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
C057	1-165-989-11	CERAMIC CHIP	10uF	10%	6.3V	
* C059	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
* C060	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
* C201	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C202	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
* C203	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	

Ref. No.	Part No.	Description				
* C204	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C205	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V	
* C206	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C208	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C211	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C212	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C213	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C214	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C215	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C216	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C217	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C218	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V	
C219	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V	
* C220	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C221	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C223	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C224	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C241	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C242	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C243	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C244	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C245	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V	
C246	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C247	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C249	1-165-799-11	TANTAL. CHIP	22uF	20%	4V	
* C251	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C252	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C253	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C256	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C257	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C259	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C260	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C261	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C262	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C263	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C264	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V	
* C265	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C266	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C267	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C268	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C281	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C282	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C283	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C284	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C286	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C288	1-100-611-91	CERAMIC CHIP	22uF	20%	6.3V	
C301	1-164-939-11	CERAMIC CHIP	0.0022uF	10%	50V	
C302	1-100-742-91	CERAMIC CHIP	2.2uF	20%	10V	
* C303	1-114-796-91	CERAMIC CHIP	4.7uF	10%	16V	
C305	1-100-756-91	CERAMIC CHIP	0.047uF		50V	
C306	1-100-591-91	CERAMIC CHIP	1uF	10%	25V	
* C307	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C308	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
* C309	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V	
C310	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V	
C312	1-128-627-11	CERAMIC CHIP	1000PF	10%	16V	
C313	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V	

Ref. No.	Part No.	Description									
* C314	1-114-582-11	CERAMIC CHIP	0.1uF	10%	16V						
* C315	1-114-582-11	CERAMIC CHIP	0.1uF	10%	16V						
* C316	1-114-582-11	CERAMIC CHIP	0.1uF	10%	16V						
* C317	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C318	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C319	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C320	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C322	1-100-962-91	TANTAL. CHIP	22uF	20%	6.3V						
C323	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C324	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
* C325	1-114-795-21	TANTAL. CHIP	22uF	20%	10V						
C326	1-112-342-91	CERAMIC CHIP	10uF	20%	10V						
C327	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C328	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C329	1-112-300-91	CERAMIC CHIP	4.7uF	10%	10V						
C330	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C331	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C332	1-112-534-11	CERAMIC CHIP	10uF	20%	6.3V						
C334	1-112-342-91	CERAMIC CHIP	10uF	20%	10V						
C337	1-100-742-91	CERAMIC CHIP	2.2uF	20%	10V						
* C338	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C339	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C341	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C342	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C343	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V						
* C505	1-114-872-91	TANTAL. CHIP	47uF	20%	10V						
* C506	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C507	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C508	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C509	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C510	1-128-628-11	CERAMIC CHIP	0.0022uF	10%	6.3V						
C511	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C513	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C514	1-128-628-11	CERAMIC CHIP	0.0022uF	10%	6.3V						
C516	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
* C521	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C522	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C523	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C524	1-114-411-21	CERAMIC CHIP	0.33uF	10%	6.3V						
C525	1-114-411-21	CERAMIC CHIP	0.33uF	10%	6.3V						
C528	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V						
C529	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V						
* C530	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C531	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C532	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C534	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C547	1-112-534-11	CERAMIC CHIP	10uF	20%	6.3V						
C548	1-165-887-91	CERAMIC CHIP	0.22uF	10%	6.3V						
C549	1-165-887-91	CERAMIC CHIP	0.22uF	10%	6.3V						
* C554	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C557	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C558	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V						
* C565	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C575	1-128-627-11	CERAMIC CHIP	1000pF	10%	16V						
C576	1-128-627-11	CERAMIC CHIP	1000pF	10%	16V						
* C577	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C578	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C579	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C580	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C581	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
* C582	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C585	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
* C586	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C603	1-128-630-11	CERAMIC CHIP	0.0047uF	10%	6.3V						
* C604	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C605	1-112-534-11	CERAMIC CHIP	10uF	20%	6.3V						
* C606	1-112-298-91	CERAMIC CHIP	1uF	10%	16V						
C607	1-119-923-11	CERAMIC CHIP	0.047uF	10%	10V						
C608	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C609	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C610	1-100-567-81	CERAMIC CHIP	0.01uF	10%	25V						
C611	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
* C612	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C613	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C614	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C615	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C616	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C617	1-112-534-11	CERAMIC CHIP	10uF	20%	6.3V						
C618	1-128-632-11	CERAMIC CHIP	0.01uF	10%	6.3V						
C619	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V						
C620	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C621	1-100-415-91	CERAMIC CHIP	0.47uF	10%	6.3V						
C622	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
C702	1-100-786-91	TANTAL. CHIP	22uF	20%	6.3V						
* C703	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V						
C705	1-112-717-91	CERAMIC CHIP	1uF	10%	6.3V						
* C706	1-112-746-11	CERAMIC CHIP	4.7uF	10%	6.3V						
C707	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C708	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C709	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C710	1-100-742-91	CERAMIC CHIP	2.2uF	20%	10V						
C711	1-100-742-91	CERAMIC CHIP	2.2uF	20%	10V						
C712	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C713	1-112-021-91	CERAMIC CHIP	2.2uF	20%	16V						
C714	1-112-299-91	CERAMIC CHIP	2.2uF	10%	16V						
C715	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C716	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C717	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C718	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C719	1-165-908-11	CERAMIC CHIP	1uF	10%	10V						
C720	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V						
< CONNECTOR >											
* CN301	1-817-942-51	CONNECTOR, FPC (ZIF) 39P									
* CN501	1-817-942-51	CONNECTOR, FPC (ZIF) 39P									
* CN701	1-820-031-51	CONNECTOR, FPC (LIF (NON-ZIF))									
CN702	1-819-611-31	MEMORY STICK DUO CONNECTOR 10P									
* CN704	1-820-634-51	CONNECTOR, FPC (LIF (NON-ZIF))									
CN705	(Not supplied)	CONNECTOR, MULTIPLE (SOCKET) (MULTI CONNECTOR)									
(CN705 is supplied including in SY-207 complete board (SERVICE).)											
* CN707	1-821-857-51	CONNECTOR, FPC (LIF (NON-ZIF))									
* CN709	1-822-111-61	CONNECTOR, FPC (ZIF) 45P									
* CN711	1-821-857-51	CONNECTOR, FPC (LIF (NON-ZIF))									
* CN712	1-820-634-51	CONNECTOR, FPC (LIF (NON-ZIF))									

Ref. No.	Part No.	Description	Ref. No.	Part No.	Description			
		< DIODE >						
* D003	6-502-150-01	DIODE MA2SD320G8S0	L008	1-457-412-11	INDUCTOR	10uH		
* D004	6-502-150-01	DIODE MA2SD320G8S0	* L241	1-481-102-21	INDUCTOR	10uH		
* D005	6-502-136-01	DIODE MA2ZD020GLS0	L301	1-400-342-21	INDUCTOR	10uH		
* D006	6-502-150-01	DIODE MA2SD320G8S0	L302	1-400-342-21	INDUCTOR	10uH		
* D007	6-502-150-01	DIODE MA2SD320G8S0	L601	1-400-342-21	INDUCTOR	10uH		
* D008	6-502-150-01	DIODE MA2SD320G8S0	* L701	1-481-102-21	INDUCTOR	10uH		
* D009	6-502-150-01	DIODE MA2SD320G8S0	* L702	1-481-102-21	INDUCTOR	10uH		
* D201	6-501-955-01	DIODE MAZS056G08S0			< LINE FILTER >			
D301	6-501-106-01	DIODE 1SS387CT (TL3SONY)	LF701	1-457-223-11	COMMON MODE CHOKE COIL			
* D603	6-501-930-01	DIODE MAZW068HGLS0			< MICROPHONE >			
D706	6-501-216-01	DIODE CL-271HR-C-TS (MS ACCESS)	MIC601	1-542-756-21	MICROPHONE			
D707	8-719-084-17	DIODE EMZ6.8ET2R			< TRANSISTOR >			
* D708	6-502-150-01	DIODE MA2SD320G8S0	Q001	6-550-791-01	TRANSISTOR	SSM3J15FV (TL3SONYZ)		
D717	8-719-084-17	DIODE EMZ6.8ET2R	Q009	6-551-202-01	TRANSISTOR	LM6K1FS8T2R		
D718	8-719-084-17	DIODE EMZ6.8ET2R	Q010	6-551-202-01	TRANSISTOR	LM6K1FS8T2R		
D719	6-501-080-01	DIODE MAZP068H0AS0	Q011	6-551-346-01	TRANSISTOR	LSK3541FS8T2L		
		< FUSE >	* Q012	6-552-065-01	TRANSISTOR	MCH6336-S-TL-E		
△ F001	1-576-415-11	FUSE (2A/32V)	* Q014	6-551-213-01	TRANSISTOR	RN1113ACT (TL3SONY)		
△ F002	1-576-843-21	FUSE (0.8A/32V)	* Q015	6-552-058-01	TRANSISTOR	MTM7632109S0		
△ F003	1-576-570-11	FUSE (0.63A/32V)	* Q016	6-552-029-01	TRANSISTOR	MCH3377-S-TL-E		
		< FERRITE BEAD >	* Q301	6-551-868-01	TRANSISTOR	UP04213G08S0		
FB201	1-400-725-21	FERRITE, EMI (SMD) (1005)	Q302	6-550-601-01	TRANSISTOR	UNRF2A300AS0		
FB202	1-400-725-21	FERRITE, EMI (SMD) (1005)	* Q706	6-550-011-01	TRANSISTOR	EMH10T2R		
FB203	1-400-725-21	FERRITE, EMI (SMD) (1005)	* Q707	6-551-209-01	TRANSISTOR	RN2902AFS (TLR3SONY)		
FB301	1-400-331-11	FERRITE, EMI (SMD) (1005)	* Q708	6-551-157-01	TRANSISTOR	2SA207900AS0		
FB302	1-400-331-11	FERRITE, EMI (SMD) (1005)			< RESISTOR >			
FB303	1-400-331-11	FERRITE, EMI (SMD) (1005)	R001	1-218-977-11	RES-CHIP	100K	5%	1/16W
FB304	1-400-331-11	FERRITE, EMI (SMD) (1005)	R004	1-218-941-81	RES-CHIP	100	5%	1/16W
		< IC >	R006	1-240-678-11	METAL CHIP	33	5%	1/20W
* IC001	6-713-492-01	IC SC901572BVOR2	R010	1-240-691-11	METAL CHIP	470	5%	1/20W
* IC201	6-807-572-01	IC uPD79F0043FC-402-2N1-E2-A	R011	1-240-707-11	METAL CHIP	10K	5%	1/20W
* IC202	6-712-166-01	IC AK8150CU-L	R012	1-240-718-11	METAL CHIP	100K	5%	1/20W
IC211	(Not supplied)	IC PRX515106A	R013	1-240-703-11	METAL CHIP	4.7K	5%	1/20W
(IC211 is supplied including in SY-207 complete board (SERVICE).)			R014	1-240-729-11	METAL CHIP	1M	5%	1/20W
* IC302	6-708-462-01	IC R1114Q231D-TR-FA	R015	1-240-724-11	METAL CHIP	330K	5%	1/20W
* IC303	6-710-911-01	IC TK70618HCL-G	R017	1-245-604-11	METAL CHIP	10M	5%	1/16W
* IC304	6-713-231-01	IC VSP2701ZRPR	R018	1-240-713-11	METAL CHIP	33K	5%	1/20W
* IC305	6-712-173-01	IC RP103K281D	R019	1-218-981-91	RES-CHIP	220K	5%	1/16W
* IC503	6-713-274-01	IC R2J30502LG	R020	1-218-939-11	RES-CHIP	68	5%	1/16W
* IC506	8-753-284-38	IC CXA3739AER-T2	R022	1-240-729-11	METAL CHIP	1M	5%	1/20W
* IC507	6-708-444-01	IC R1114Q281D-TR-FA	R023	1-240-714-11	METAL CHIP	47K	5%	1/20W
* IC601	6-709-313-01	IC AN12918A-VB	R024	1-240-736-91	METAL CHIP	10	0.5%	1/20W
* IC602	6-712-173-01	IC RP103K281D	R029	1-218-981-91	RES-CHIP	220K	5%	1/16W
		< COIL >	R030	1-218-945-11	RES-CHIP	220	5%	1/16W
* L001	1-457-566-11	INDUCTOR 4.3uH	R031	1-240-707-11	METAL CHIP	10K	5%	1/20W
L002	1-457-412-11	INDUCTOR 10uH	R033	1-240-830-11	METAL CHIP	100K	0.5%	1/20W
L003	1-481-097-11	INDUCTOR 4.7uH	R053	1-240-726-11	METAL CHIP	470K	5%	1/20W
L004	1-457-412-11	INDUCTOR 10uH	R054	1-240-729-11	METAL CHIP	1M	5%	1/20W
L005	1-457-412-11	INDUCTOR 10uH	R055	1-240-726-11	METAL CHIP	470K	5%	1/20W
L006	1-400-676-11	INDUCTOR 22uH	R059	1-240-729-11	METAL CHIP	1M	5%	1/20W
L007	1-457-412-11	INDUCTOR 10uH	R066	1-216-864-11	SHORT CHIP	0		
			R202	1-218-931-11	RES-CHIP	15	5%	1/16W

• Refer to page 5-1 for mark △.

Ref. No.	Part No.	Description				Ref. No.	Part No.	Description			
R212	1-240-707-11	METAL CHIP	10K	5%	1/20W	R515	1-240-808-11	METAL CHIP	10K	0.5%	1/20W
R213	1-240-695-11	METAL CHIP	1K	5%	1/20W	R517	1-240-718-11	METAL CHIP	100K	5%	1/20W
R214	1-240-695-11	METAL CHIP	1K	5%	1/20W	* R524	1-245-673-11	METAL CHIP	330K	0.5%	1/20W
R215	1-240-760-91	METAL CHIP	100	0.5%	1/20W	* R525	1-245-673-11	METAL CHIP	330K	0.5%	1/20W
* R216	1-240-779-91	METAL CHIP	620	0.5%	1/20W	R526	1-240-808-11	METAL CHIP	10K	0.5%	1/20W
R217	1-240-683-11	METAL CHIP	100	5%	1/20W	R527	1-240-808-11	METAL CHIP	10K	0.5%	1/20W
R218	1-240-683-11	METAL CHIP	100	5%	1/20W	R528	1-240-820-11	METAL CHIP	33K	0.5%	1/20W
R219	1-240-683-11	METAL CHIP	100	5%	1/20W	R529	1-240-820-11	METAL CHIP	33K	0.5%	1/20W
R220	1-240-683-11	METAL CHIP	100	5%	1/20W	R530	1-240-713-11	METAL CHIP	33K	5%	1/20W
R221	1-240-683-11	METAL CHIP	100	5%	1/20W	R531	1-240-713-11	METAL CHIP	33K	5%	1/20W
R222	1-240-683-11	METAL CHIP	100	5%	1/20W	R544	1-240-784-91	METAL CHIP	1K	0.5%	1/20W
R253	1-240-676-11	METAL CHIP	22	5%	1/20W	R545	1-240-784-91	METAL CHIP	1K	0.5%	1/20W
R254	1-240-676-11	METAL CHIP	22	5%	1/20W	R558	1-240-714-11	METAL CHIP	47K	5%	1/20W
R255	1-240-718-11	METAL CHIP	100K	5%	1/20W	R572	1-240-689-11	METAL CHIP	330	5%	1/20W
R260	1-240-766-11	METAL CHIP	180	0.5%	1/20W	R573	1-240-689-11	METAL CHIP	330	5%	1/20W
R261	1-240-764-91	METAL CHIP	150	0.5%	1/20W	R574	1-240-810-11	METAL CHIP	12K	0.5%	1/20W
R262	1-240-764-91	METAL CHIP	150	0.5%	1/20W	R580	1-240-695-11	METAL CHIP	1K	5%	1/20W
* R263	1-240-792-91	METAL CHIP	2.2K	0.5%	1/20W	R581	1-240-695-11	METAL CHIP	1K	5%	1/20W
R264	1-240-695-11	METAL CHIP	1K	5%	1/20W	R603	1-240-707-11	METAL CHIP	10K	5%	1/20W
* R266	1-240-792-91	METAL CHIP	2.2K	0.5%	1/20W	R604	1-240-714-11	METAL CHIP	47K	5%	1/20W
R267	1-240-824-91	METAL CHIP	56K	0.5%	1/20W	R608	1-218-939-11	RES-CHIP	68	5%	1/16W
R268	1-240-824-91	METAL CHIP	56K	0.5%	1/20W	R609	1-240-707-11	METAL CHIP	10K	5%	1/20W
* R269	1-240-797-91	METAL CHIP	3.6K	0.5%	1/20W	R707	1-240-695-11	METAL CHIP	1K	5%	1/20W
R270	1-240-784-91	METAL CHIP	1K	0.5%	1/20W	R709	1-240-695-11	METAL CHIP	1K	5%	1/20W
R271	1-240-784-91	METAL CHIP	1K	0.5%	1/20W	R710	1-240-695-11	METAL CHIP	1K	5%	1/20W
R272	1-240-707-11	METAL CHIP	10K	5%	1/20W	R712	1-240-695-11	METAL CHIP	1K	5%	1/20W
R273	1-240-830-11	METAL CHIP	100K	0.5%	1/20W	R713	1-240-715-11	METAL CHIP	56K	5%	1/20W
R274	1-240-830-11	METAL CHIP	100K	0.5%	1/20W	R714	1-240-695-11	METAL CHIP	1K	5%	1/20W
R279	1-240-714-11	METAL CHIP	47K	5%	1/20W	R717	1-240-695-11	METAL CHIP	1K	5%	1/20W
R286	1-240-718-11	METAL CHIP	100K	5%	1/20W	R718	1-240-695-11	METAL CHIP	1K	5%	1/20W
R287	1-240-729-11	METAL CHIP	1M	5%	1/20W	R729	1-694-535-11	SHORT CHIP	0		
R289	1-208-943-11	METAL CHIP	220K	0.5%	1/16W	R732	1-240-687-11	METAL CHIP	220	5%	1/20W
R290	1-240-714-11	METAL CHIP	47K	5%	1/20W						
R294	1-208-943-11	METAL CHIP	220K	0.5%	1/16W			< SENSOR >			
R301	1-208-949-11	METAL CHIP	390K	0.5%	1/16W	SE001	1-480-956-11	SENSOR, MAGNETIC (SHUTTER DOOR DETECT)			
R302	1-208-920-11	METAL CHIP	24K	0.5%	1/16W	SE510	1-480-628-31	SENSOR, ANGULAR VELOCITY (21kHz/23kHz) (PITCH/YAW SENSOR)			
R303	1-694-535-11	SHORT CHIP	0								
R304	1-240-729-11	METAL CHIP	1M	5%	1/20W			< VIBRATOR >			
R305	1-240-719-11	METAL CHIP	120K	5%	1/20W	X001	1-781-525-11	VIBRATOR, CRYSTAL (32.768kHz)			
R306	1-240-718-11	METAL CHIP	100K	5%	1/20W	* X201	1-813-904-21	QUARTZ CRYSTAL OSCILLATOR (38MHz)			
R307	1-218-990-11	SHORT CHIP	0								
R308	1-218-990-11	SHORT CHIP	0								
R309	1-218-990-11	SHORT CHIP	0								
R310	1-218-990-11	SHORT CHIP	0								
R311	1-218-990-11	SHORT CHIP	0								
R312	1-218-990-11	SHORT CHIP	0								
R501	1-240-818-11	METAL CHIP	27K	0.5%	1/20W						
* R502	1-245-671-11	METAL CHIP	39K	0.5%	1/20W						
R504	1-240-820-11	METAL CHIP	33K	0.5%	1/20W						
R505	1-240-806-11	METAL CHIP	8.2K	0.5%	1/20W						
* R506	1-240-790-91	METAL CHIP	1.8K	0.5%	1/20W						
R507	1-240-808-11	METAL CHIP	10K	0.5%	1/20W						
R508	1-240-818-11	METAL CHIP	27K	0.5%	1/20W						
* R509	1-245-671-11	METAL CHIP	39K	0.5%	1/20W						
R512	1-240-820-11	METAL CHIP	33K	0.5%	1/20W						
R513	1-240-806-11	METAL CHIP	8.2K	0.5%	1/20W						
* R514	1-240-790-91	METAL CHIP	1.8K	0.5%	1/20W						

